



RELIABILITY REPORT  
FOR  
MAX9926UAEE+  
PLASTIC ENCAPSULATED DEVICES

May 20, 2009

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
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<b>Approved by</b>
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## Conclusion

The MAX9926UAEE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX9924-MAX9927 variable reluctance (VR or magnetic coil) sensor interface devices are ideal for position and speed sensing for automotive crankshafts, camshafts, transmission shafts, etc. These devices integrate a precision amplifier and comparator with selectable adaptive peak threshold and zero-crossing circuit blocks that generate robust output pulses even in the presence of substantial system noise or extremely weak VR signals. The MAX9926/MAX9927 are dual versions of the MAX9924/MAX9925, respectively. The MAX9924/MAX9926 combine matched resistors with a CMOS input precision operational amplifier to give high CMRR over a wide range of input frequencies and temperatures. The MAX9924/MAX9926 differential amplifiers provide a fixed gain of 1V/V. The MAX9925/MAX9927 make all three terminals of the internal operational amplifier available, allowing greater flexibility for gain. The MAX9926 also provides a direction output that is useful for quadrature-connected VR sensors that are used in certain high-performance engines. These devices interface with both new-generation differential VR sensors as well as legacy single-ended VR sensors. The MAX9924/MAX9925 are available in the 10-pin  $\mu$ MAX® package, while the MAX9926/MAX9927 are available in the 16-pin QSOP package. All devices are specified over the -40°C to +125°C automotive temperature range.

## II. Manufacturing Information

A. Description/Function:	Variable-Reluctance Sensor Interface with Differential Input and Adaptive Peak Threshold
B. Process:	S4
C. Number of Device Transistors:	3074
D. Fabrication Location:	Texas
E. Assembly Location:	Carsem Malaysia, ATP Philippines, UTL Thailand
F. Date of Initial Production:	January 24, 2009

## III. Packaging Information

A. Package Type:	16-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Au (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	103.7°C/W
M. Multi Layer Theta Jc:	37°C/W

## IV. Die Information

A. Dimensions:	38 X 85 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/0.5% Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.4 \times 10^{-9}$$

$$\lambda = 22.4 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the S4 Process results in a FIT Rate of 4.6 @ 25C and 79.2 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The OY26 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA, 1.5x VCCMax Overvoltage per JESD78.

**Table 1**  
Reliability Evaluation Test Results

**MAX9926UAEE+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data